PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company	577	STMicroelectronics International N.V
1.2 PCN No.		MDG/19/10689
1.3 Title of PCN		ASE Kaohsiung (Taiwan) additional source for LQFP 14x14 package products
1.4 Product Category		LQFP 14x14 listed products
1.5 Issue date		2019-01-21

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	FRANK SCHIFANO	
2.1.2 Phone	+1 5148333778	
2.1.3 Email	frank.schifano@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung Taiwan	

4. Description of change			
	Old	New	
4.1 Description	Back-end sources: - ST Muar Malaysia - Amkor ATP Philippines	Back-end sources: - ST Muar Malaysia - Amkor ATP Philippines - ASE Kaohsiung Taiwan - Additional source For more information, please refer to PCN10689 – Additional information attached document.	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Lead color and surface finish change depending on leadfinishing. Package darkness changes depending on molding compound. Pin1 identifier might change in terms of form and positioning. Marking position and size could be different upon assembly site, without any loss of information.		

5. Reason / motivation for change		
	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.	
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change		
6.1 Description	Change is visible through assembly traceability plant, in the marking: - "9H" for ST Muar Malaysia - "7B" for Amkor ATP Philippines - "AA" for ASE Kaohsiung Taiwan Please refer to PCN 10689 – Additional information attached document.	

7. Timing / schedule		
7.1 Date of qualification results	2019-01-18	
7.2 Intended start of delivery	2019-02-18	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
3.1 Description 10689 MDG-MCD-RER1810 PCN10548 PCN10689-ASE Kaohsiung additional source for LQFP 7x710x1014x1420x20.pdf			
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-01-21

9. Attachments (additional documentations)

10689 Public product.pdf 10689 MDG-MCD-RER1810 PCN10548 PCN10689-ASE Kaohsiung additional source for LQFP 7x710x1014x1420x20.pdf 10689 PCN10689_Additional information.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	STM32F407VGT6		
	STM32F767VGT6		

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